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### Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

### Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

#### Details

Product Status	Active
Number of LABs/CLBs	56480
Number of Logic Elements/Cells	149500
Total RAM Bits	7880704
Number of I/O	240
Number of Gates	-
Voltage - Supply	1.07V ~ 1.13V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	484-LFBGA
Supplier Device Package	484-MBGA (15x15)
Purchase URL	<a href="https://www.e-xfl.com/product-detail/intel/5cgxfc7b6m15i7n">https://www.e-xfl.com/product-detail/intel/5cgxfc7b6m15i7n</a>



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## Cyclone V Device Overview

The Cyclone® V devices are designed to simultaneously accommodate the shrinking power consumption, cost, and time-to-market requirements; and the increasing bandwidth requirements for high-volume and cost-sensitive applications.

Enhanced with integrated transceivers and hard memory controllers, the Cyclone V devices are suitable for applications in the industrial, wireless and wireline, military, and automotive markets.

### Related Information

[Cyclone V Device Handbook: Known Issues](#)

Lists the planned updates to the Cyclone V Device Handbook chapters.

## Key Advantages of Cyclone V Devices

**Table 1. Key Advantages of the Cyclone V Device Family**

Advantage	Supporting Feature
Lower power consumption	<ul style="list-style-type: none"> <li>Built on TSMC's 28 nm low-power (28LP) process technology and includes an abundance of hard intellectual property (IP) blocks</li> <li>Up to 40% lower power consumption than the previous generation device</li> </ul>
Improved logic integration and differentiation capabilities	<ul style="list-style-type: none"> <li>8-input adaptive logic module (ALM)</li> <li>Up to 13.59 megabits (Mb) of embedded memory</li> <li>Variable-precision digital signal processing (DSP) blocks</li> </ul>
Increased bandwidth capacity	<ul style="list-style-type: none"> <li>3.125 gigabits per second (Gbps) and 6.144 Gbps transceivers</li> <li>Hard memory controllers</li> </ul>
Hard processor system (HPS) with integrated Arm* Cortex*-A9 MPCore* processor	<ul style="list-style-type: none"> <li>Tight integration of a dual-core Arm Cortex-A9 MPCore processor, hard IP, and an FPGA in a single Cyclone V system-on-a-chip (SoC)</li> <li>Supports over 128 Gbps peak bandwidth with integrated data coherency between the processor and the FPGA fabric</li> </ul>
Lowest system cost	<ul style="list-style-type: none"> <li>Requires only two core voltages to operate</li> <li>Available in low-cost wirebond packaging</li> <li>Includes innovative features such as Configuration via Protocol (CvP) and partial reconfiguration</li> </ul>

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## Summary of Cyclone V Features

**Table 2. Summary of Features for Cyclone V Devices**

Feature	Description	
Technology	<ul style="list-style-type: none"> <li>TSMC's 28-nm low-power (28LP) process technology</li> <li>1.1 V core voltage</li> </ul>	
Packaging	<ul style="list-style-type: none"> <li>Wirebond low-halogen packages</li> <li>Multiple device densities with compatible package footprints for seamless migration between different device densities</li> <li>RoHS-compliant and leaded<sup>(1)</sup> options</li> </ul>	
High-performance FPGA fabric	Enhanced 8-input ALM with four registers	
Internal memory blocks	<ul style="list-style-type: none"> <li>M10K—10-kilobits (Kb) memory blocks with soft error correction code (ECC)</li> <li>Memory logic array block (MLAB)—640-bit distributed LUTRAM where you can use up to 25% of the ALMs as MLAB memory</li> </ul>	
Embedded Hard IP blocks	Variable-precision DSP	<ul style="list-style-type: none"> <li>Native support for up to three signal processing precision levels (three 9 x 9, two 18 x 18, or one 27 x 27 multiplier) in the same variable-precision DSP block</li> <li>64-bit accumulator and cascade</li> <li>Embedded internal coefficient memory</li> <li>Padder/subtractor for improved efficiency</li> </ul>
	Memory controller	DDR3, DDR2, and LPDDR2 with 16 and 32 bit ECC support
	Embedded transceiver I/O	PCI Express* (PCIe*) Gen2 and Gen1 (x1, x2, or x4) hard IP with multifunction support, endpoint, and root port
Clock networks	<ul style="list-style-type: none"> <li>Up to 550 MHz global clock network</li> <li>Global, quadrant, and peripheral clock networks</li> <li>Clock networks that are not used can be powered down to reduce dynamic power</li> </ul>	
Phase-locked loops (PLLs)	<ul style="list-style-type: none"> <li>Precision clock synthesis, clock delay compensation, and zero delay buffering (ZDB)</li> <li>Integer mode and fractional mode</li> </ul>	
FPGA General-purpose I/Os (GPIOs)	<ul style="list-style-type: none"> <li>875 megabits per second (Mbps) LVDS receiver and 840 Mbps LVDS transmitter</li> <li>400 MHz/800 Mbps external memory interface</li> <li>On-chip termination (OCT)</li> <li>3.3 V support with up to 16 mA drive strength</li> </ul>	
Low-power high-speed serial interface	<ul style="list-style-type: none"> <li>614 Mbps to 6.144 Gbps integrated transceiver speed</li> <li>Transmit pre-emphasis and receiver equalization</li> <li>Dynamic partial reconfiguration of individual channels</li> </ul>	
HPS (Cyclone V SE, SX, and ST devices only)	<ul style="list-style-type: none"> <li>Single or dual-core Arm Cortex-A9 MPCore processor-up to 925 MHz maximum frequency with support for symmetric and asymmetric multiprocessing</li> <li>Interface peripherals—10/100/1000 Ethernet media access control (EMAC), USB 2.0 On-The-Go (OTG) controller, quad serial peripheral interface (QSPI) flash controller, NAND flash controller, Secure Digital/MultiMediaCard (SD/MMC) controller, UART, controller area network (CAN), serial peripheral interface (SPI), I<sup>2</sup>C interface, and up to 85 HPS GPIO interfaces</li> <li>System peripherals—general-purpose timers, watchdog timers, direct memory access (DMA) controller, FPGA configuration manager, and clock and reset managers</li> <li>On-chip RAM and boot ROM</li> </ul>	

*continued...*

<sup>(1)</sup> Contact Intel for availability.



## Available Options

**Figure 1. Sample Ordering Code and Available Options for Cyclone V E Devices**

The SEU internal scrubbing feature is available for Cyclone V E, GX, SE, and SX devices with the "SC" suffix in the part number. For device availability and ordering, contact your local Intel sales representatives.



## Maximum Resources

**Table 4. Maximum Resource Counts for Cyclone V E Devices**

Resource		Member Code				
		A2	A4	A5	A7	A9
Logic Elements (LE) (K)		25	49	77	150	301
ALM		9,430	18,480	29,080	56,480	113,560
Register		37,736	73,920	116,320	225,920	454,240
Memory (Kb)	M10K	1,760	3,080	4,460	6,860	12,200
	MLAB	196	303	424	836	1,717
Variable-precision DSP Block		25	66	150	156	342
18 x 18 Multiplier		50	132	300	312	684
PLL		4	4	6	7	8
GPIO		224	224	240	480	480
LVDS	Transmitter	56	56	60	120	120
	Receiver	56	56	60	120	120
Hard Memory Controller		1	1	2	2	2



## Available Options

**Figure 3. Sample Ordering Code and Available Options for Cyclone V GT Devices**



## Maximum Resources

**Table 8. Maximum Resource Counts for Cyclone V GT Devices**

Resource		Member Code		
		D5	D7	D9
Logic Elements (LE) (K)		77	150	301
ALM		29,080	56,480	113,560
Register		116,320	225,920	454,240
Memory (Kb)	M10K	4,460	6,860	12,200
	MLAB	424	836	1,717
Variable-precision DSP Block		150	156	342
18 x 18 Multiplier		300	312	684
PLL		6	7	8
6 Gbps Transceiver		6	9	12
GPIO <sup>(5)</sup>		336	480	560
LVDS	Transmitter	84	120	140

*continued...*

<sup>(5)</sup> The number of GPIOs does not include transceiver I/Os. In the Intel Quartus Prime software, the number of user I/Os includes transceiver I/Os.



## Cyclone V SE

This section provides the available options, maximum resource counts, and package plan for the Cyclone V SE devices.

The information in this section is correct at the time of publication. For the latest information and to get more details, refer to the *Product Selector Guide*.

### Related Information

#### Product Selector Guide

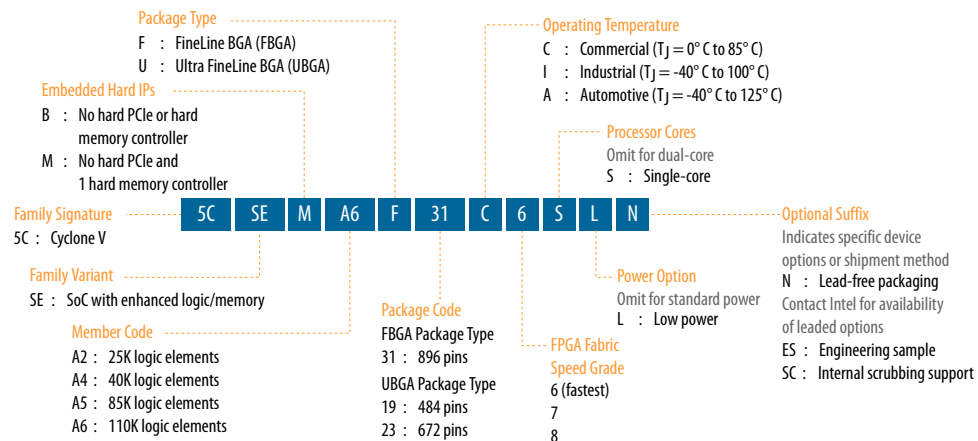
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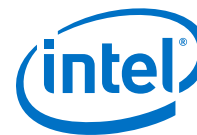
## Available Options

### Figure 4. Sample Ordering Code and Available Options for Cyclone V SE Devices

The SEU internal scrubbing feature is available for Cyclone V E, GX, SE, and SX devices with the "SC" suffix in the part number. For device availability and ordering, contact your local Intel sales representatives.

Cyclone V SE and SX low-power devices (L power option) offer 30% static power reduction for devices with 25K LE and 40K LE, and 20% static power reduction for devices with 85K LE and 110K LE.





## Maximum Resources

**Table 10. Maximum Resource Counts for Cyclone V SE Devices**

Resource		Member Code			
		A2	A4	A5	A6
Logic Elements (LE) (K)		25	40	85	110
ALM		9,430	15,880	32,070	41,910
Register		37,736	60,376	128,300	166,036
Memory (Kb)	M10K	1,400	2,700	3,970	5,570
	MLAB	138	231	480	621
Variable-precision DSP Block		36	84	87	112
18 x 18 Multiplier		72	168	174	224
FPGA PLL		5	5	6	6
HPS PLL		3	3	3	3
FPGA GPIO		145	145	288	288
HPS I/O		181	181	181	181
LVDS	Transmitter	32	32	72	72
	Receiver	37	37	72	72
FPGA Hard Memory Controller		1	1	1	1
HPS Hard Memory Controller		1	1	1	1
Arm Cortex-A9 MPCore Processor		Single- or dual-core	Single- or dual-core	Single- or dual-core	Single- or dual-core

### Related Information

[True LVDS Buffers in Devices, I/O Features in Cyclone V Devices](#)

Provides the number of LVDS channels in each device package.

## Package Plan

**Table 11. Package Plan for Cyclone V SE Devices**

The HPS I/O counts are the number of I/Os in the HPS and does not correlate with the number of HPS-specific I/O pins in the FPGA. Each HPS-specific pin in the FPGA may be mapped to several HPS I/Os.

Member Code	U484 (19 mm)		U672 (23 mm)		F896 (31 mm)	
	FPGA GPIO	HPS I/O	FPGA GPIO	HPS I/O	FPGA GPIO	HPS I/O
A2	66	151	145	181	—	—
A4	66	151	145	181	—	—
A5	66	151	145	181	288	181
A6	66	151	145	181	288	181





## Cyclone V SX

This section provides the available options, maximum resource counts, and package plan for the Cyclone V SX devices.

The information in this section is correct at the time of publication. For the latest information and to get more details, refer to the *Product Selector Guide*.

### Related Information

#### Product Selector Guide

Provides the latest information about Intel products.

## Available Options

### Figure 5. Sample Ordering Code and Available Options for Cyclone V SX Devices

The SEU internal scrubbing feature is available for Cyclone V E, GX, SE, and SX devices with the "SC" suffix in the part number. For device availability and ordering, contact your local Intel sales representatives.

Cyclone V SE and SX low-power devices (L power option) offer 30% static power reduction for devices with 25K LE and 40K LE, and 20% static power reduction for devices with 85K LE and 110K LE.



## Maximum Resources

**Table 12. Maximum Resource Counts for Cyclone V SX Devices**

Resource		Member Code			
		C2	C4	C5	C6
Logic Elements (LE) (K)		25	40	85	110
ALM		9,430	15,880	32,070	41,910
Register		37,736	60,376	128,300	166,036
Memory (Kb)	M10K	1,400	2,700	3,970	5,570
	MLAB	138	231	480	621
Variable-precision DSP Block		36	84	87	112
18 x 18 Multiplier		72	168	174	224
FPGA PLL		5	5	6	6

*continued...*



Resource		Member Code			
		C2	C4	C5	C6
HPS PLL		3	3	3	3
3 Gbps Transceiver		6	6	9	9
FPGA GPIO <sup>(8)</sup>		145	145	288	288
HPS I/O		181	181	181	181
LVDS	Transmitter	32	32	72	72
	Receiver	37	37	72	72
PCIe Hard IP Block		2	2	2 <sup>(9)</sup>	2 <sup>(9)</sup>
FPGA Hard Memory Controller		1	1	1	1
HPS Hard Memory Controller		1	1	1	1
Arm Cortex-A9 MPCore Processor		Dual-core	Dual-core	Dual-core	Dual-core

### Related Information

#### True LVDS Buffers in Devices, I/O Features in Cyclone V Devices

Provides the number of LVDS channels in each device package.

## Package Plan

**Table 13. Package Plan for Cyclone V SX Devices**

The HPS I/O counts are the number of I/Os in the HPS and does not correlate with the number of HPS-specific I/O pins in the FPGA. Each HPS-specific pin in the FPGA may be mapped to several HPS I/Os.

Member Code	U672 (23 mm)			F896 (31 mm)		
	FPGA GPIO	HPS I/O	XCVR	FPGA GPIO	HPS I/O	XCVR
C2	145	181	6	—	—	—
C4	145	181	6	—	—	—
C5	145	181	6	288	181	9
C6	145	181	6	288	181	9

## Cyclone V ST

This section provides the available options, maximum resource counts, and package plan for the Cyclone V ST devices.

The information in this section is correct at the time of publication. For the latest information and to get more details, refer to the *Product Selector Guide*.

<sup>(8)</sup> The number of GPIOs does not include transceiver I/Os. In the Intel Quartus Prime software, the number of user I/Os includes transceiver I/Os.

<sup>(9)</sup> 1 PCIe Hard IP Block in U672 package.



Resource		Member Code	
		D5	D6
	Receiver	72	72
PCIe Hard IP Block		2	2
FPGA Hard Memory Controller		1	1
HPS Hard Memory Controller		1	1
Arm Cortex-A9 MPCore Processor		Dual-core	Dual-core

### Related Information

[True LVDS Buffers in Devices, I/O Features in Cyclone V Devices](#)

Provides the number of LVDS channels in each device package.

## Package Plan

**Table 15. Package Plan for Cyclone V ST Devices**

- The HPS I/O counts are the number of I/Os in the HPS and does not correlate with the number of HPS-specific I/O pins in the FPGA. Each HPS-specific pin in the FPGA may be mapped to several HPS I/Os.
- Transceiver counts shown are for transceiver  $\leq 5$  Gbps. 6 Gbps transceiver channel count support depends on the package and channel usage. For more information about the 6 Gbps transceiver channel count, refer to the *Cyclone V Device Handbook Volume 2: Transceivers*.

Member Code	F896 (31 mm)		
	FPGA GPIO	HPS I/O	XCVR
D5	288	181	9 <sup>(11)</sup>
D6	288	181	9 <sup>(11)</sup>

### Related Information

[6.144-Gbps Support Capability in Cyclone V GT Devices, Cyclone V Device Handbook Volume 2: Transceivers](#)

Provides more information about 6 Gbps transceiver channel count.

<sup>(11)</sup> If you require CPRI (at 4.9152 Gbps) and PCIe Gen2 transmit jitter compliance, Intel recommends that you use only up to seven full-duplex transceiver channels for CPRI, and up to six full-duplex channels for PCIe Gen2. The CMU channels are not considered full-duplex channels.

**Table 16. Variable-Precision DSP Block Configurations for Cyclone V Devices**

Usage Example	Multiplier Size (Bit)	DSP Block Resource
Low precision fixed point for video applications	Three 9 x 9	1
Medium precision fixed point in FIR filters	Two 18 x 18	1
FIR filters and general DSP usage	Two 18 x 18 with accumulate	1
High precision fixed- or floating-point implementations	One 27 x 27 with accumulate	1

You can configure each DSP block during compilation as independent three 9 x 9, two 18 x 18, or one 27 x 27 multipliers. With a dedicated 64 bit cascade bus, you can cascade multiple variable-precision DSP blocks to implement even higher precision DSP functions efficiently.

**Table 17. Number of Multipliers in Cyclone V Devices**

The table lists the variable-precision DSP resources by bit precision for each Cyclone V device.

Variant	Member Code	Variable-precision DSP Block	Independent Input and Output Multiplications Operator			18 x 18 Multiplier Adder Mode	18 x 18 Multiplier Adder Summed with 36 bit Input
			9 x 9 Multiplier	18 x 18 Multiplier	27 x 27 Multiplier		
Cyclone V E	A2	25	75	50	25	25	25
	A4	66	198	132	66	66	66
	A5	150	450	300	150	150	150
	A7	156	468	312	156	156	156
	A9	342	1,026	684	342	342	342
Cyclone V GX	C3	57	171	114	57	57	57
	C4	70	210	140	70	70	70
	C5	150	450	300	150	150	150
	C7	156	468	312	156	156	156
	C9	342	1,026	684	342	342	342
Cyclone V GT	D5	150	450	300	150	150	150
	D7	156	468	312	156	156	156
	D9	342	1,026	684	342	342	342
Cyclone V SE	A2	36	108	72	36	36	36
	A4	84	252	168	84	84	84
	A5	87	261	174	87	87	87
	A6	112	336	224	112	112	112
Cyclone V SX	C2	36	108	72	36	36	36
	C4	84	252	168	84	84	84
	C5	87	261	174	87	87	87
continued...							



Variant	Member Code	Variable-precision DSP Block	Independent Input and Output Multiplications Operator			18 x 18 Multiplier Adder Mode	18 x 18 Multiplier Adder Summed with 36 bit Input
			9 x 9 Multiplier	18 x 18 Multiplier	27 x 27 Multiplier		
	C6	112	336	224	112	112	112
Cyclone V ST	D5	87	261	174	87	87	87
	D6	112	336	224	112	112	112

## Embedded Memory Blocks

The embedded memory blocks in the devices are flexible and designed to provide an optimal amount of small- and large-sized memory arrays to fit your design requirements.

## Types of Embedded Memory

The Cyclone V devices contain two types of memory blocks:

- 10 Kb M10K blocks—blocks of dedicated memory resources. The M10K blocks are ideal for larger memory arrays while still providing a large number of independent ports.
- 640 bit memory logic array blocks (MLABs)—enhanced memory blocks that are configured from dual-purpose logic array blocks (LABs). The MLABs are ideal for wide and shallow memory arrays. The MLABs are optimized for implementation of shift registers for digital signal processing (DSP) applications, wide shallow FIFO buffers, and filter delay lines. Each MLAB is made up of ten adaptive logic modules (ALMs). In the Cyclone V devices, you can configure these ALMs as ten 32 x 2 blocks, giving you one 32 x 20 simple dual-port SRAM block per MLAB.

## Embedded Memory Capacity in Cyclone V Devices

**Table 18. Embedded Memory Capacity and Distribution in Cyclone V Devices**

Variant	Member Code	M10K		MLAB		Total RAM Bit (Kb)
		Block	RAM Bit (Kb)	Block	RAM Bit (Kb)	
Cyclone V E	A2	176	1,760	314	196	1,956
	A4	308	3,080	485	303	3,383
	A5	446	4,460	679	424	4,884
	A7	686	6,860	1338	836	7,696
	A9	1,220	12,200	2748	1,717	13,917
Cyclone V GX	C3	135	1,350	291	182	1,532
	C4	250	2,500	678	424	2,924
	C5	446	4,460	678	424	4,884
	C7	686	6,860	1338	836	7,696
	C9	1,220	12,200	2748	1,717	13,917
continued...						



Variant	Member Code	M10K		MLAB		Total RAM Bit (Kb)
		Block	RAM Bit (Kb)	Block	RAM Bit (Kb)	
Cyclone V GT	D5	446	4,460	679	424	4,884
	D7	686	6,860	1338	836	7,696
	D9	1,220	12,200	2748	1,717	13,917
Cyclone V SE	A2	140	1,400	221	138	1,538
	A4	270	2,700	370	231	2,460
	A5	397	3,970	768	480	4,450
	A6	553	5,530	994	621	6,151
Cyclone V SX	C2	140	1,400	221	138	1,538
	C4	270	2,700	370	231	2,460
	C5	397	3,970	768	480	4,450
	C6	553	5,530	994	621	6,151
Cyclone V ST	D5	397	3,970	768	480	4,450
	D6	553	5,530	994	621	6,151

## Embedded Memory Configurations

**Table 19. Supported Embedded Memory Block Configurations for Cyclone V Devices**

This table lists the maximum configurations supported for the embedded memory blocks. The information is applicable only to the single-port RAM and ROM modes.

Memory Block	Depth (bits)	Programmable Width
MLAB	32	x16, x18, or x20
M10K	256	x40 or x32
	512	x20 or x16
	1K	x10 or x8
	2K	x5 or x4
	4K	x2
	8K	x1

## Clock Networks and PLL Clock Sources

550 MHz Cyclone V devices have 16 global clock networks capable of up to operation. The clock network architecture is based on Intel's global, quadrant, and peripheral clock structure. This clock structure is supported by dedicated clock input pins and fractional PLLs.

**Note:** To reduce power consumption, the Intel Quartus Prime software identifies all unused sections of the clock network and powers them down.

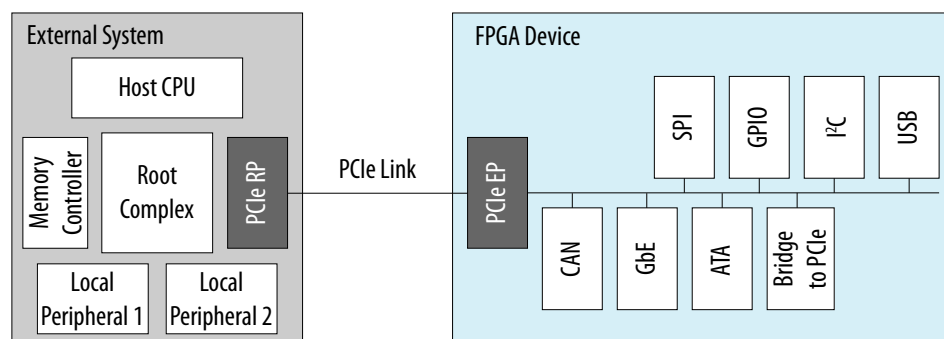
## PCIe Gen1 and Gen2 Hard IP

Cyclone V GX, GT, SX, and ST devices contain PCIe hard IP that is designed for performance and ease-of-use. The PCIe hard IP consists of the MAC, data link, and transaction layers.

The PCIe hard IP supports PCIe Gen2 and Gen1 end point and root port for up to x4 lane configuration. The PCIe Gen2 x4 support is PCIe-compatible.

The PCIe endpoint support includes multifunction support for up to eight functions, as shown in the following figure. The integrated multifunction support reduces the FPGA logic requirements by up to 20,000 LEs for PCIe designs that require multiple peripherals.

**Figure 9. PCIe Multifunction for Cyclone V Devices**



The Cyclone V PCIe hard IP operates independently from the core logic. This independent operation allows the PCIe link to wake up and complete link training in less than 100 ms while the Cyclone V device completes loading the programming file for the rest of the device.

In addition, the PCIe hard IP in the Cyclone V device provides improved end-to-end datapath protection using ECC.

## External Memory Interface

This section provides an overview of the external memory interface in Cyclone V devices.

### Hard and Soft Memory Controllers

Cyclone V devices support up to two hard memory controllers for DDR3, DDR2, and LPDDR2 SDRAM devices. Each controller supports 8 to 32 bit components of up to 4 gigabits (Gb) in density with two chip selects and optional ECC. For the Cyclone V SoC devices, an additional hard memory controller in the HPS supports DDR3, DDR2, and LPDDR2 SDRAM devices.

All Cyclone V devices support soft memory controllers for DDR3, DDR2, and LPDDR2 SDRAM devices for maximum flexibility.



## External Memory Performance

**Table 20. External Memory Interface Performance in Cyclone V Devices**

The maximum and minimum operating frequencies depend on the memory interface standards and the supported delay-locked loop (DLL) frequency listed in the device datasheet.

Interface	Voltage (V)	Maximum Frequency (MHz)		Minimum Frequency (MHz)
		Hard Controller	Soft Controller	
DDR3 SDRAM	1.5	400	303	303
	1.35	400	303	303
DDR2 SDRAM	1.8	400	300	167
LPDDR2 SDRAM	1.2	333	300	167

### Related Information

#### External Memory Interface Spec Estimator

For the latest information and to estimate the external memory system performance specification, use Intel's External Memory Interface Spec Estimator tool.

## HPS External Memory Performance

**Table 21. HPS External Memory Interface Performance**

The hard processor system (HPS) is available in Cyclone V SoC devices only.

Interface	Voltage (V)	HPS Hard Controller (MHz)
DDR3 SDRAM	1.5	400
	1.35	400
DDR2 SDRAM	1.8	400
LPDDR2 SDRAM	1.2	333

### Related Information

#### External Memory Interface Spec Estimator

For the latest information and to estimate the external memory system performance specification, use Intel's External Memory Interface Spec Estimator tool.

## Low-Power Serial Transceivers

Cyclone V devices deliver the industry's lowest power 6.144 Gbps transceivers at an estimated 88 mW maximum power consumption per channel. Cyclone V transceivers are designed to be compliant with a wide range of protocols and data rates.

## Transceiver Channels

The transceivers are positioned on the left outer edge of the device. The transceiver channels consist of the physical medium attachment (PMA), physical coding sublayer (PCS), and clock networks.





## PCS Features

The Cyclone V core logic connects to the PCS through an 8, 10, 16, 20, 32, or 40 bit interface, depending on the transceiver data rate and protocol. Cyclone V devices contain PCS hard IP to support PCIe Gen1 and Gen2, Gbps Ethernet (GbE), Serial RapidIO® (SRIO), and Common Public Radio Interface (CPRI).

Most of the standard and proprietary protocols from 614 Mbps to 6.144 Gbps are supported.

**Table 23. Transceiver PCS Features for Cyclone V Devices**

PCS Support	Data Rates (Gbps)	Transmitter Data Path Feature	Receiver Data Path Feature
3-Gbps and 6-Gbps Basic	0.614 to 6.144	<ul style="list-style-type: none"> <li>Phase compensation FIFO</li> <li>Byte serializer</li> <li>8B/10B encoder</li> <li>Transmitter bit-slip</li> </ul>	<ul style="list-style-type: none"> <li>Word aligner</li> <li>Deskew FIFO</li> <li>Rate-match FIFO</li> <li>8B/10B decoder</li> <li>Byte deserializer</li> <li>Byte ordering</li> <li>Receiver phase compensation FIFO</li> </ul>
PCIe Gen1 (x1, x2, x4)	2.5 and 5.0	<ul style="list-style-type: none"> <li>Dedicated PCIe PHY IP core</li> <li>PIPE 2.0 interface to the core logic</li> </ul>	<ul style="list-style-type: none"> <li>Dedicated PCIe PHY IP core</li> <li>PIPE 2.0 interface to the core logic</li> </ul>
PCIe Gen2 (x1, x2, x4) <sup>(12)</sup>			
GbE	1.25	<ul style="list-style-type: none"> <li>Custom PHY IP core with preset feature</li> <li>GbE transmitter synchronization state machine</li> </ul>	<ul style="list-style-type: none"> <li>Custom PHY IP core with preset feature</li> <li>GbE receiver synchronization state machine</li> </ul>
XAUI <sup>(13)</sup>	3.125	<ul style="list-style-type: none"> <li>Dedicated XAUI PHY IP core</li> <li>XAUI synchronization state machine for bonding four channels</li> </ul>	<ul style="list-style-type: none"> <li>Dedicated XAUI PHY IP core</li> <li>XAUI synchronization state machine for realigning four channels</li> </ul>
HiGig	3.75		
SRIO 1.3 and 2.1	1.25 to 3.125	<ul style="list-style-type: none"> <li>Custom PHY IP core with preset feature</li> <li>SRIO version 2.1-compliant x2 and x4 channel bonding</li> </ul>	<ul style="list-style-type: none"> <li>Custom PHY IP core with preset feature</li> <li>SRIO version 2.1-compliant x2 and x4 deskew state machine</li> </ul>
SDI, SD/HD, and 3G-SDI	0.27 <sup>(14)</sup> , 1.485, and 2.97	Custom PHY IP core with preset feature	Custom PHY IP core with preset feature
JESD204A	0.3125 <sup>(15)</sup> to 3.125		

*continued...*

<sup>(12)</sup> PCIe Gen2 is supported for Cyclone V GT and ST devices. The PCIe Gen2 x4 support is PCIe-compatible.

<sup>(13)</sup> XAUI is supported through the soft PCS.

<sup>(14)</sup> The 0.27-Gbps data rate is supported using oversampling user logic that you must implement in the FPGA fabric.

<sup>(15)</sup> The 0.3125-Gbps data rate is supported using oversampling user logic that you must implement in the FPGA fabric.

## HPS-FPGA AXI Bridges

The HPS-FPGA bridges, which support the Advanced Microcontroller Bus Architecture (AMBA®) Advanced eXtensible Interface (AXI™) specifications, consist of the following bridges:

- FPGA-to-HPS AXI bridge—a high-performance bus supporting 32, 64, and 128 bit data widths that allows the FPGA fabric to issue transactions to slaves in the HPS.
- HPS-to-FPGA AXI bridge—a high-performance bus supporting 32, 64, and 128 bit data widths that allows the HPS to issue transactions to slaves in the FPGA fabric.
- Lightweight HPS-to-FPGA AXI bridge—a lower latency 32 bit width bus that allows the HPS to issue transactions to slaves in the FPGA fabric. This bridge is primarily used for control and status register (CSR) accesses to peripherals in the FPGA fabric.

The HPS-FPGA AXI bridges allow masters in the FPGA fabric to communicate with slaves in the HPS logic, and vice versa. For example, the HPS-to-FPGA AXI bridge allows you to share memories instantiated in the FPGA fabric with one or both microprocessors in the HPS, while the FPGA-to-HPS AXI bridge allows logic in the FPGA fabric to access the memory and peripherals in the HPS.

Each HPS-FPGA bridge also provides asynchronous clock crossing for data transferred between the FPGA fabric and the HPS.

## HPS SDRAM Controller Subsystem

The HPS SDRAM controller subsystem contains a multiport SDRAM controller and DDR PHY that are shared between the FPGA fabric (through the FPGA-to-HPS SDRAM interface), the level 2 (L2) cache, and the level 3 (L3) system interconnect. The FPGA-to-HPS SDRAM interface supports AMBA AXI and Avalon® Memory-Mapped (Avalon-MM) interface standards, and provides up to six individual ports for access by masters implemented in the FPGA fabric.

To maximize memory performance, the SDRAM controller subsystem supports command and data reordering, deficit round-robin arbitration with aging, and high-priority bypass features. The SDRAM controller subsystem supports DDR2, DDR3, or LPDDR2 devices up to 4 Gb in density operating at up to 400 MHz (800 Mbps data rate).

## FPGA Configuration and Processor Booting

The FPGA fabric and HPS in the SoC are powered independently. You can reduce the clock frequencies or gate the clocks to reduce dynamic power, or shut down the entire FPGA fabric to reduce total system power.

You can configure the FPGA fabric and boot the HPS independently, in any order, providing you with more design flexibility:

- You can boot the HPS independently. After the HPS is running, the HPS can fully or partially reconfigure the FPGA fabric at any time under software control. The HPS can also configure other FPGAs on the board through the FPGA configuration controller.
- You can power up both the HPS and the FPGA fabric together, configure the FPGA fabric first, and then boot the HPS from memory accessible to the FPGA fabric.



**Note:** Although the FPGA fabric and HPS are on separate power domains, the HPS must remain powered up during operation while the FPGA fabric can be powered up or down as required.

#### **Related Information**

##### [Cyclone V Device Family Pin Connection Guidelines](#)

Provides detailed information about power supply pin connection guidelines and power regulator sharing.

## **Hardware and Software Development**

For hardware development, you can configure the HPS and connect your soft logic in the FPGA fabric to the HPS interfaces using the Platform Designer (Standard) system integration tool in the Intel Quartus Prime software.

For software development, the Arm-based SoC devices inherit the rich software development ecosystem available for the Arm Cortex-A9 MPCore processor. The software development process for Intel SoCs follows the same steps as those for other SoC devices from other manufacturers. Support for Linux, VxWorks®, and other operating systems is available for the SoCs. For more information on the operating systems support availability, contact the Intel sales team.

You can begin device-specific firmware and software development on the Intel SoC Virtual Target. The Virtual Target is a fast PC-based functional simulation of a target development system—a model of a complete development board that runs on a PC. The Virtual Target enables the development of device-specific production software that can run unmodified on actual hardware.

#### **Related Information**

##### [International Altera Sales Support Offices](#)

## **Dynamic and Partial Reconfiguration**

The Cyclone V devices support dynamic reconfiguration and partial reconfiguration.

### **Dynamic Reconfiguration**

The dynamic reconfiguration feature allows you to dynamically change the transceiver data rates, PMA settings, or protocols of a channel, without affecting data transfer on adjacent channels. This feature is ideal for applications that require on-the-fly multiprotocol or multirate support. You can reconfigure the PMA and PCS blocks with dynamic reconfiguration.

### **Partial Reconfiguration**

**Note:** The partial reconfiguration feature is available for Cyclone V E, GX, SE, and SX devices with the "SC" suffix in the part number. For device availability and ordering, contact your local Intel sales representatives.

Partial reconfiguration allows you to reconfigure part of the device while other sections of the device remain operational. This capability is important in systems with critical uptime requirements because it allows you to make updates or adjust functionality without disrupting services.



## Power Management

Leveraging the FPGA architectural features, process technology advancements, and transceivers that are designed for power efficiency, the Cyclone V devices consume less power than previous generation Cyclone FPGAs:

- Total device core power consumption—less by up to 40%.
- Transceiver channel power consumption—less by up to 50%.

Additionally, Cyclone V devices contain several hard IP blocks that reduce logic resources and deliver substantial power savings of up to 25% less power than equivalent soft implementations.

## Document Revision History for Cyclone V Device Overview

Document Version	Changes
2018.05.07	<ul style="list-style-type: none"> <li>• Added the low power option ("L" suffix) for Cyclone V SE and Cyclone V SX devices in the <i>Sample Ordering Code and Available Options</i> diagrams.</li> <li>• Rebranded as Intel.</li> </ul>

Date	Version	Changes
December 2017	2017.12.18	<ul style="list-style-type: none"> <li>• Updated ALM resources for Cyclone V E, Cyclone V SE, Cyclone V SX, and Cyclone V ST devices.</li> </ul>
June 2016	2016.06.10	Updated Cyclone V GT speed grade to -7 in Sample Ordering Code and Available Options for Cyclone V GT Devices diagram.
December 2015	2015.12.21	<ul style="list-style-type: none"> <li>• Added descriptions to package plan tables for Cyclone V GT and ST devices.</li> <li>• Changed instances of <i>Quartus II</i> to <i>Quartus Prime</i>.</li> </ul>
June 2015	2015.06.12	<ul style="list-style-type: none"> <li>• Replaced a note to partial reconfiguration feature. Note: The partial reconfiguration feature is available for Cyclone V E, GX, SE, and SX devices with the "SC" suffix in the part number. For device availability and ordering, contact your local Altera sales representatives.</li> <li>• Updated logic elements (LE) (K) for the following devices: <ul style="list-style-type: none"> <li>— Cyclone V E A7: Updated from 149.5 to 150</li> <li>— Cyclone V GX C3: Updated from 35.5 to 36</li> <li>— Cyclone V GX C7: Updated from 149.7 to 150</li> <li>— Cyclone V GT D7: Updated from 149.5 to 150</li> </ul> </li> <li>• Updated MLAB (Kb) in Maximum Resource Counts for Cyclone V GX Devices table as follows: <ul style="list-style-type: none"> <li>— Cyclone V GX C3: Updated from 291 to 182</li> <li>— Cyclone V GX C4: Updated from 678 to 424</li> <li>— Cyclone V GX C5: Updated from 678 to 424</li> <li>— Cyclone V GX C7: Updated from 1,338 to 836</li> <li>— Cyclone V GX C9: Updated from 2,748 to 1,717</li> </ul> </li> </ul>

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Date	Version	Changes
		<ul style="list-style-type: none"> <li>Updated Figure 1, Figure 2, Figure 3, Figure 4, Figure 5, Figure 6, and Figure 10.</li> <li>Updated the "FPGA Configuration and Processor Booting" and "Hardware and Software Development" sections.</li> <li>Text edits throughout the document.</li> </ul>
February 2012	1.2	<ul style="list-style-type: none"> <li>Updated Table 1-2, Table 1-3, and Table 1-6.</li> <li>Updated "Cyclone V Family Plan" on page 1-4 and "Clock Networks and PLL Clock Sources" on page 1-15.</li> <li>Updated Figure 1-1 and Figure 1-6.</li> </ul>
November 2011	1.1	<ul style="list-style-type: none"> <li>Updated Table 1-1, Table 1-2, Table 1-3, Table 1-4, Table 1-5, and Table 1-6.</li> <li>Updated Figure 1-4, Figure 1-5, Figure 1-6, Figure 1-7, and Figure 1-8.</li> <li>Updated "System Peripherals" on page 1-18, "HPS-FPGA AXI Bridges" on page 1-19, "HPS SDRAM Controller Subsystem" on page 1-19, "FPGA Configuration and Processor Booting" on page 1-19, and "Hardware and Software Development" on page 1-20.</li> <li>Minor text edits.</li> </ul>
October 2011	1.0	Initial release.